## LNJ811R88RA

### Hight Bright Surface Mounting Chip LED

3216 Type

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	$P_{\mathrm{D}}$	50	mW	
Forward current	$I_{\mathrm{F}}$	20	mA	
Pulse forward current *	$I_{FP}$	100	mA	
Reverse voltage	V <sub>R</sub>	4	V	
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

Note) \*: The condition of I<sub>FP</sub> is duty 10%, Pulse width 1 msec.

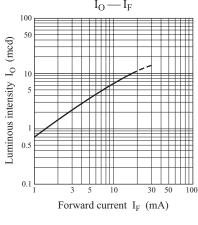
#### ■ Lighting Color

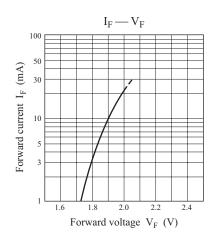
• Orange

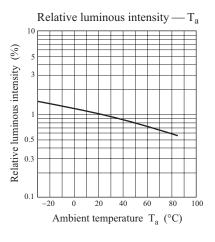
#### ■ Electro-Optical Characteristics $T_a = 25$ °C±3°C

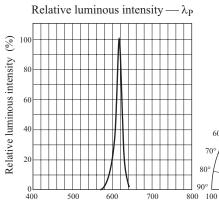
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity *	I <sub>O</sub>	$I_F = 10 \text{ mA}$	3.5	6.5		mcd
Reverse current	$I_R$	$V_R = 4 V$			100	μΑ
Forward voltage	V <sub>F</sub>	$I_F = 10 \text{ mA}$		1.9	2.5	V
Peak emission wavelength	$\lambda_{\mathrm{P}}$	$I_F = 10 \text{ mA}$		620		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		17		nm

Note) \*: Measurement tolerance: ±20%

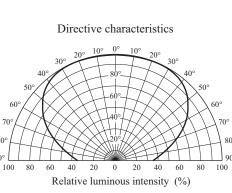


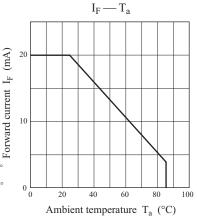






Peak emission wavelength  $\,\lambda_P\,\,(nm)$ 

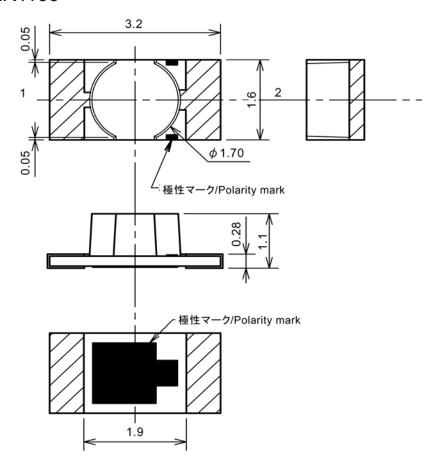




LNJ811R88RA Panasonic

■ Package (Unit: mm)

## KLTFTN2K1100



- Pin name
  - 1: Anode
  - 2: Cathode

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